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(12) **United States Design Patent** (10) **Patent No.:** **US D971,862 S**  
**Inagaki et al.** (45) **Date of Patent:** **\*\* Dec. 6, 2022**

(54) **HEATSINK**  
(71) Applicant: **Furukawa Electric Co., Ltd.**, Tokyo (JP)  
(72) Inventors: **Yoshikatsu Inagaki**, Tokyo (JP); **Shuta Hikichi**, Tokyo (JP); **Hiroshi Sakai**, Tokyo (JP)  
(73) Assignee: **Furukawa Electric Co., Ltd.**, Tokyo (JP)

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*Primary Examiner* — April Rivas  
(74) *Attorney, Agent, or Firm* — Dorsey & Whitney LLP

(57) **CLAIM**

We claim the ornamental design for a heatsink, as shown and described.

**DESCRIPTION**

FIG. 1 shows a top isometric view of a heatsink in accordance with the present design.  
FIG. 2 shows a bottom isometric view of the heatsink in FIG. 1.  
FIG. 3 shows a top view of the heatsink in FIG. 1.  
FIG. 4 shows a bottom view of the heatsink in FIG. 1.  
FIG. 5 shows a right side view of the heatsink in FIG. 1.  
FIG. 6 shows a left side view of the heatsink in FIG. 1.  
FIG. 7 shows a front view of the heatsink in FIG. 1; and, FIG. 8 shows a rear view of the heatsink in FIG. 1.  
The even broken lines illustrate environment and form no part of the claimed design. The dot-dash broken lines represent boundary lines and form no part of the claimed design.

**1 Claim, 6 Drawing Sheets**

(\*\*) Term: **15 Years**

(21) Appl. No.: **29/696,679**

(22) Filed: **Jun. 28, 2019**

(30) **Foreign Application Priority Data**

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(51) **LOC (13) Cl.** ..... **13-03**

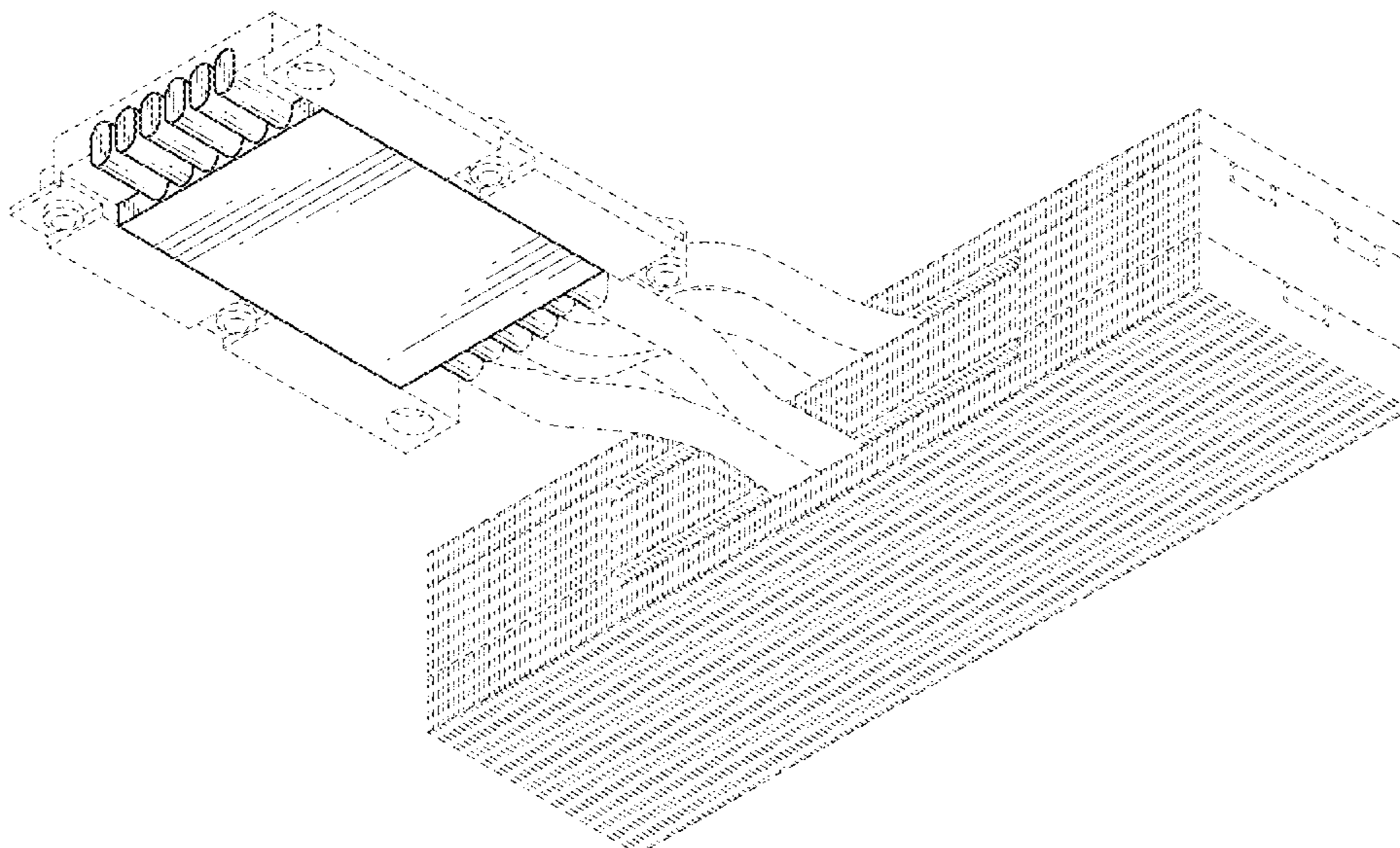
(52) **U.S. Cl.**  
USPC ..... **D13/179**

(58) **Field of Classification Search**  
USPC ..... D13/179, 182; D23/231; D14/230  
CPC . H01Q 1/428; H01Q 1/02; H01Q 1/38; H01L 23/367; H01L 23/3672; H05K 7/20254; F28F 3/022; F28F 3/04; F28F 21/065; G02B 1/111; F28D 15/0275  
See application file for complete search history.

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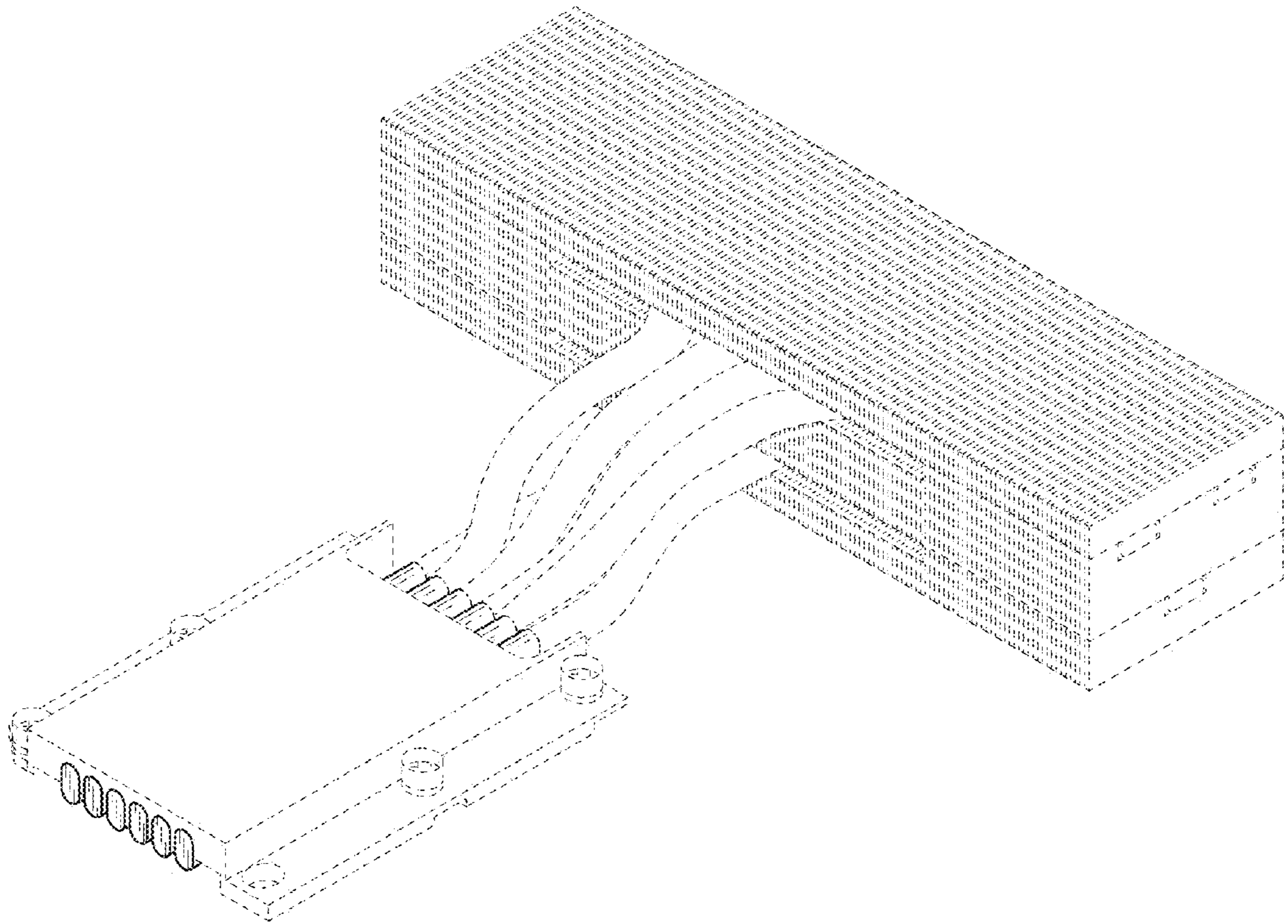


FIG. 1

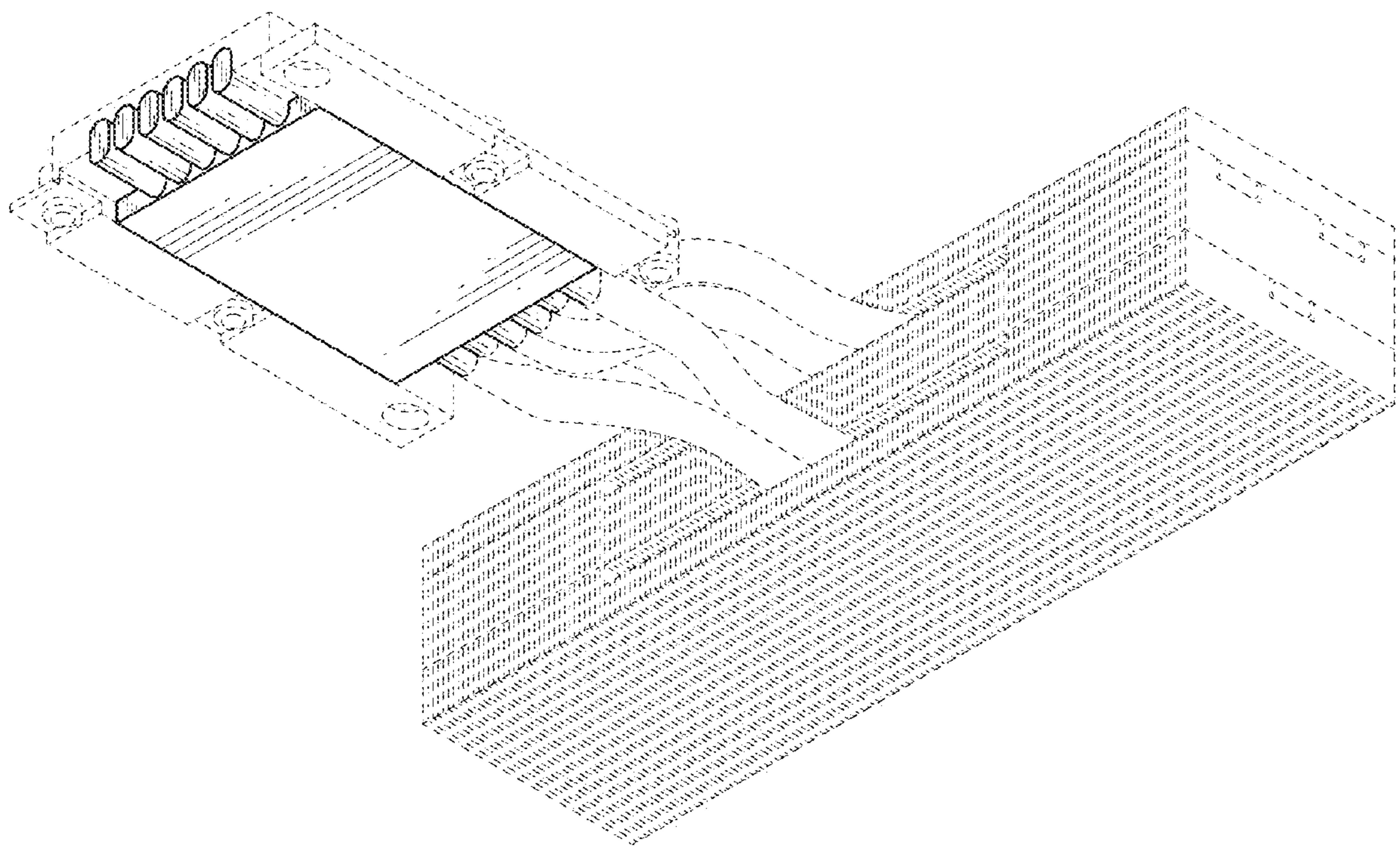
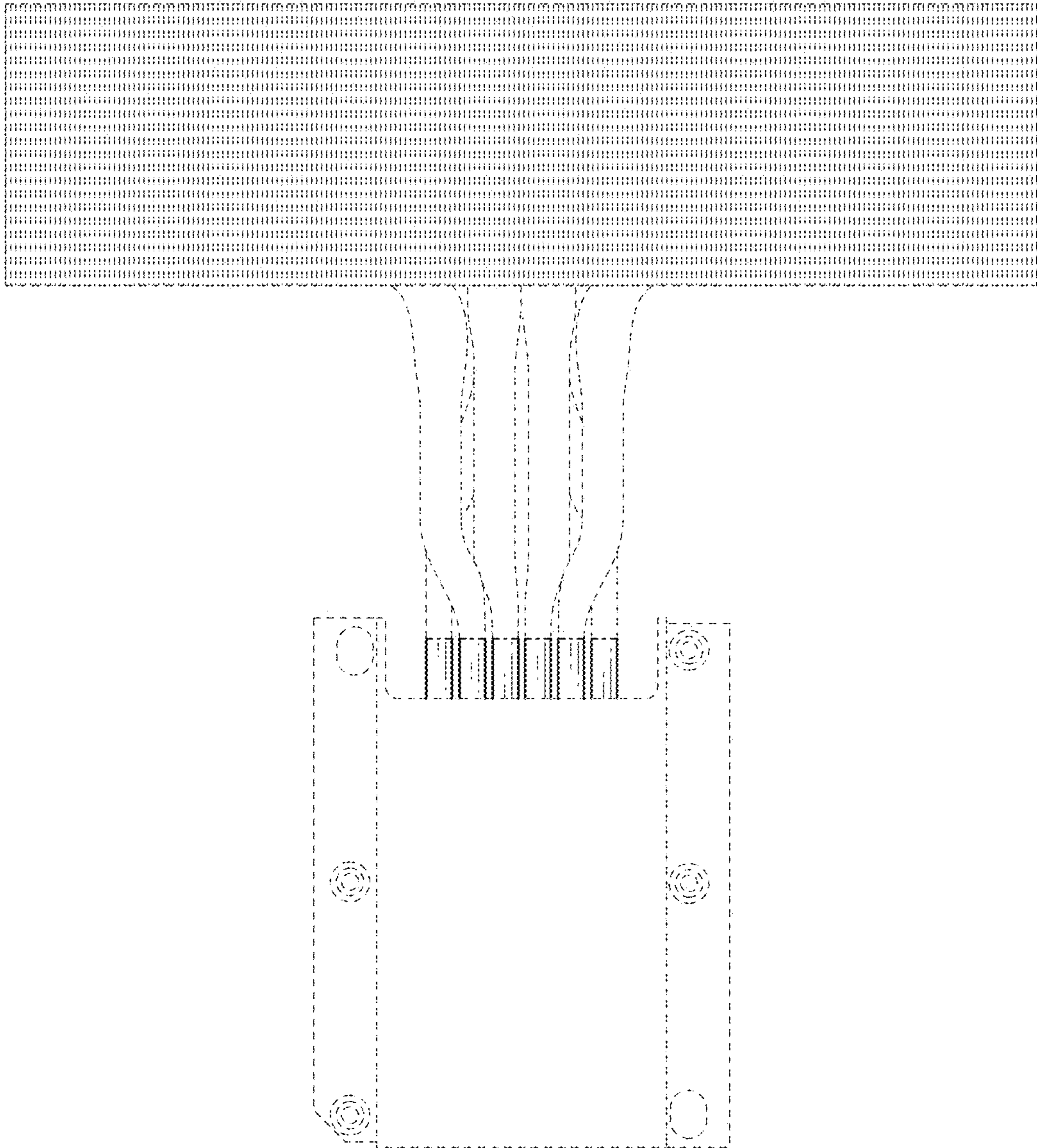


FIG. 2



*FIG. 3*

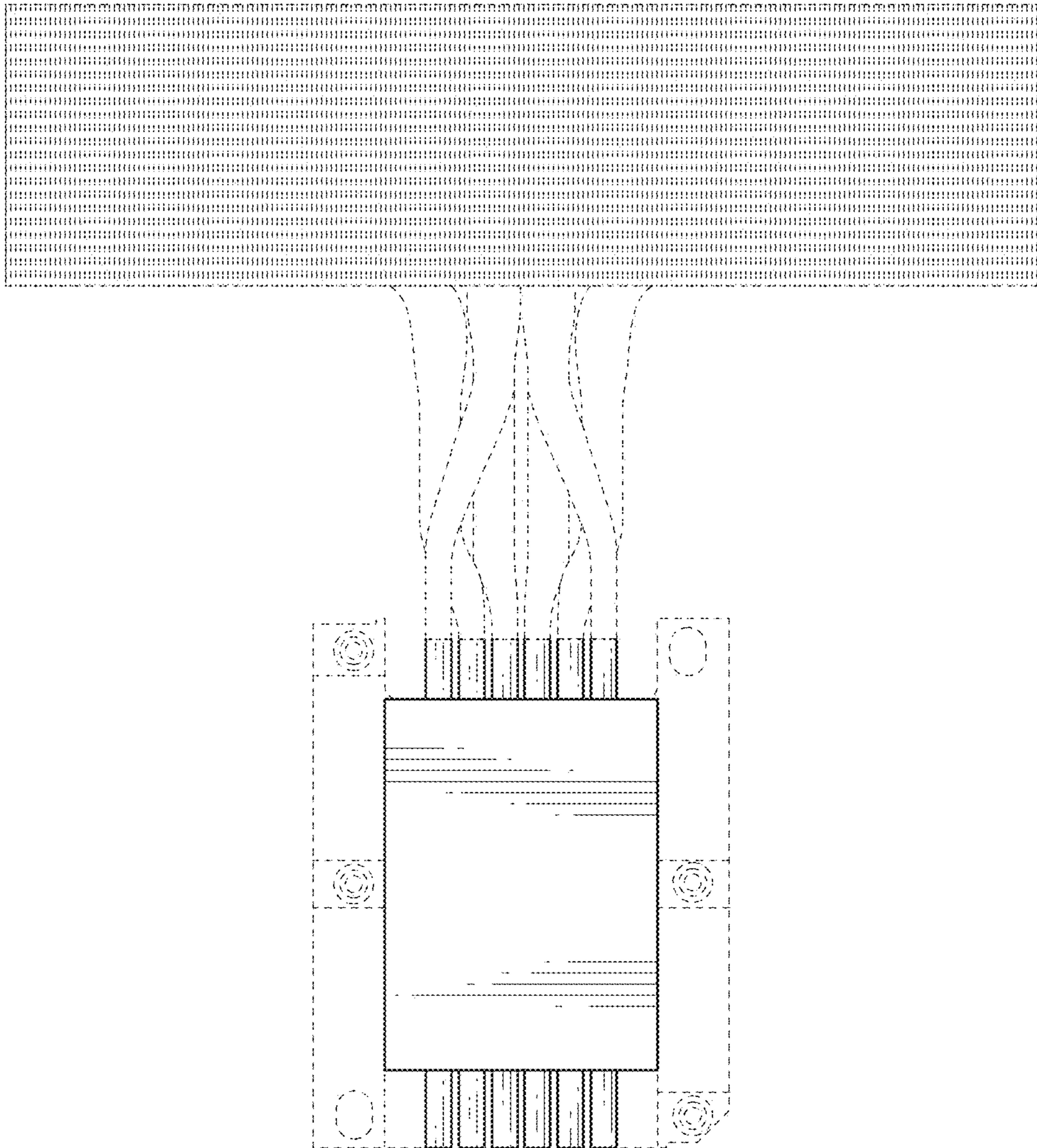


FIG. 4

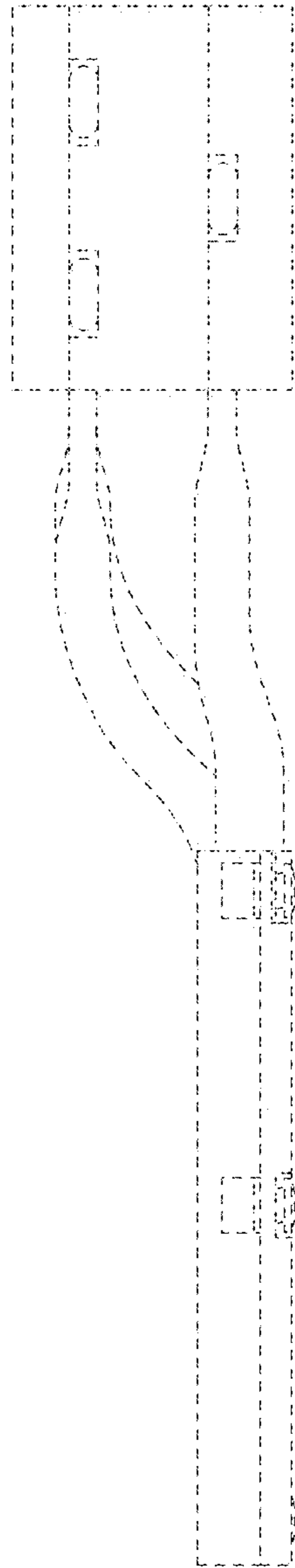


FIG. 5

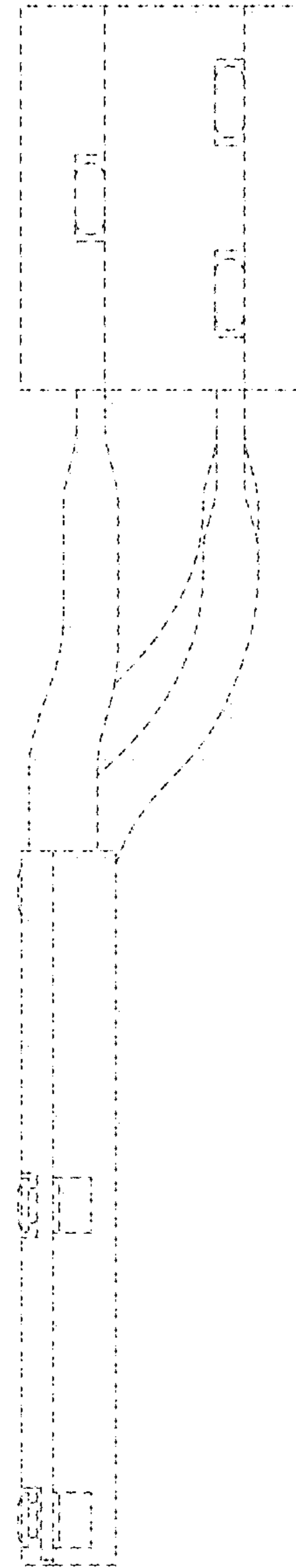
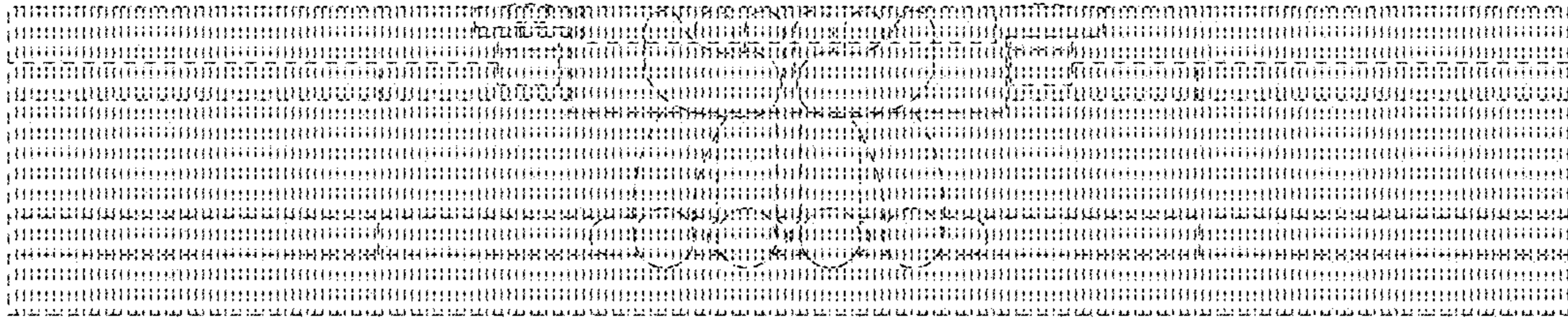
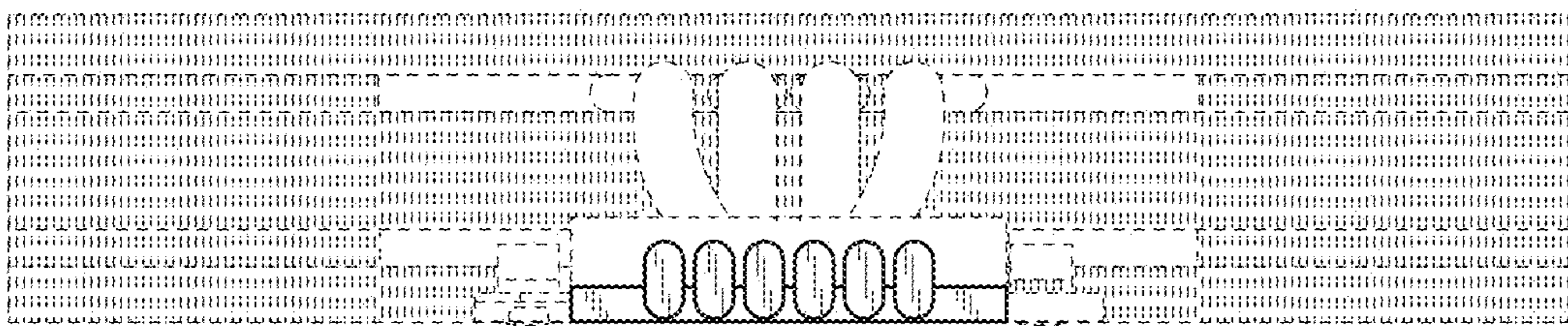


FIG. 6



*FIG. 7*



*FIG. 8*